INTEGRATED CIRCUITS



Product specification File under Integrated Circuits, IC02 September 1988



TDA3826

GENERAL DESCRIPTION

The TDA3826 is a single FM demodulator system with mute and 6 dB AF amplifier.

Features

- Supply voltage range from 4.5 V to 13.2 V
- AC coupled AF stage
- AF operational amplifier output with offset compensated input stage
- High AF output voltage with low distortion
- High ripple rejection
- Low switching noise between AF and mute

QUICK REFERENCE DATA

PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply voltage (pin 11)		VP	4.5	5.0	13.2	V
Supply current (pin 11)						
	V _P = 5.0 V	I _P	-	16	_	mA
	V _P = 12 V	I _P	-	18	_	mA
FM demodulator						
AF output voltage (pin 5)						
(RMS value)	$\Delta f = 50 \text{ kHz};$ Q _B = 11	V ₅₋₁	_	0.5	_	V
Signal plus weighted-noise						
to weighted-noise ratio		(S + W)/W	65	70	_	dB
Total harmonic distortion		THD	-	0.3	-	%
AF switch						
AF output voltage (pin 12)						
(RMS value)	$\begin{array}{l} THD \leq 0.1\%; \\ G_v = 6 \ dB \end{array}$	V ₁₂₋₁	_	1.0	_	V

PACKAGE OUTLINE

14-lead DIL; plastic (SOT27); SOT27-1; 1996 November 27.



TDA3826

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

PARAMETER	CONDITIONS	SYMBOL	MIN.	MAX.	UNIT
Supply voltage (pin 11)		V _P	4.5	13.2	V
External DC load resistance		RL	5	_	kΩ
Total power dissipation		P _{tot}	-	400	mW
Storage temperature range		T _{stg}	-25	+125	°C
Operating ambient temperature range		T _{amb}	0	+70	°C

TDA3826

CHARACTERISTICS

 V_P = 5 V; T_{amb} = 25 °C; V_i = 10 mV; f_o = 5.5 MHz; f_{AF} = 1 kHz; Δf = 50 kHz; all parameters were measured with the test circuit of Fig.2; unless otherwise specified

PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply voltage (pin 11)		V _P	4.5	5.0	13.2	V
Total current consumption		I _{tot}	-	16	20	mA
Limiting amplifier						
Input voltage (pin 14)						
(RMS value)						
		V ₁₄₋₁	-	-	200	mV
	3 dB signal reduction	V ₁₄₋₁	-	-	50	μV
DC voltages						
pin 2		V ₂₋₁	-	2	-	V
pin 13		V ₁₃₋₁	-	2	-	V
pin 14		V ₁₄₋₁	-	2	-	V
Input resistance		R ₁₄₋₁₃	-	620	-	Ω
FM demodulator						
DC voltages						
pin 7		V ₇₋₁	-	3.2	-	V
pin 8		V ₈₋₁	-	3.2	-	V
AF output voltage (pin 5)						
(RMS value)	Q _B = 11	V ₅₋₁	-	0.5	-	V
AM suppression	$f_{AM} = 400 \text{ Hz}; m = 0.3;$ $V_i = 500 \mu\text{V(rms)}$	α_{AM}	50	-	-	dB
Total harmonic distortion		THD	-	0.3	-	%
Output impedance (pin 5)		Z ₅₋₁	-	6	-	kΩ
Signal plus weighted-noise						
to weighted-noise ratio	in accordance with DIN4505; CCIR468-3	(S + W)/W	65	70	-	dB
Signal plus noise-to-noise ratio	B _{noise} = 20 kHz	(S + N)/N	75	80	-	dB
Residual RF signal (pin 5)						
(RMS value)	$2 \times f_o$ without de-emphasis	V ₅₋₁	-	30	-	mV
Ripple rejection	f _R = 70 Hz; V _R = 100 mV(p-p)	α_{R}	40	45	-	dB

PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
AF switch (pin 12)						
Open loop gain		G _{ol}	50	60	-	dB
Noise output voltage						
(RMS value)	B _{noise} = 20 kHz	V ₁₂₋₁	_	20	-	μV
Slew rate		$\frac{\Delta V_{12-1}}{\Delta t}$	2	-	_	V/µs
Maximum AF output voltage						
(RMS value)	THD \leq 0.1%; G _v = 6 dB	V ₁₂₋₁	1.1	-	-	V
Input impedance						
(pin 4)		Z ₄₋₁	50	_	_	kΩ
(pin 10)		Z ₁₀₋₁	50	_	_	kΩ
–1 dB small signal bandwidth		B _{af}	100	_	_	kHz
DC output current		I ₁₂	_	-	1	mA
Output load capacitance		CL	_	-	500	pF
Feedback resistor						
(pin 3 to pin 12)		R ₃₋₁₂	0	-	-	Ω
DC output voltage		V ₁₂₋₁	_	2.27	-	V
AF suppression in case of mute		α_{mute}	70	76	-	dB
Mute control	see Fig.3					
Mute control voltage (pin 10)						
Input (pin 4) active						
input voltage		V ₁₀₋₁	1/3 V _P	_	2/3 V _P -0.7	V
input current		I ₁₀	-200	_	+ 200	μA
Mute active						
input voltage		V ₁₀₋₁	0	_	1/3 V _P –1	V
input current		I ₁₀	10	_	500	μA
input voltage		V ₁₀₋₁	2/3 V _P + 0.7	-	VP	V
input current		I ₁₀	-600	-	-40	μA
Input voltage at pin 10						
for $I_{10} = 0 \ \mu A$		V ₁₀₋₁	_	$\frac{V_{P}-0.7}{2}$	_	V







TDA3826

Single FM TV-sound demodulator circuit

APPLICATION INFORMATION



PACKAGE OUTLINE

DIP14: plastic dual in-line package; 14 leads (300 mil)



Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE	REFERENCES			EUROPEAN ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1330E DATE	
SOT27-1	050G04	MO-001AA				92-11-17 95-03-11	

TDA3826

SOT27-1

TDA3826

SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

Soldering by dipping or by wave

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

Repairing soldered joints

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not

more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

DEFINITIONS

Data sheet status						
Objective specification	Dbjective specification This data sheet contains target or goal specifications for product development.					
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.					
Product specification	n This data sheet contains final product specifications.					
Limiting values						
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.						
Application information						
Where application informati	on is given, it is advisory and does not form part of the specification.					

LIFE SUPPORT APPLICATIONS

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